L Number	Hits	Search Text	DB	Time stamp
1	2	("6378759").PN.	USPAT;	2003/12/30
1		(03/0/39 / .PN.	US-PGPUB;	10:09
			EPO; JPO;	10.03
			DERWENT;]
}		+	IBM TDB	
_	2054	(438/612).ccls. or (438/597).ccls. and	USPAT;	2003/12/30
	2004	@ad<=20020109	US-PGPUB;	10:09
		Gad \	EPO; JPO;	10.03
			DERWENT;	
			IBM TDB	
_	337	((438/612).ccls. or (438/597).ccls. and	USPAT;	2002/08/21
	00,	@ad<=20020109) and copper and aluminum	US-PGPUB;	11:04
		Can Doubleto, and tripped and allerance	EPO; JPO;	
		•	DERWENT;	
			IBM TDB	
_	74	((438/612).ccls. or (438/597).ccls. and	USPĀT;	2003/01/23
		@ad<=20020109) and 'bonding pad' with	US-PGPUB;	10:01
		'integrated circuit'	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1		USPAT;	2002/08/21
		@ad<=20020109) and Cu adj bonding adj pad	US-PGPUB;	11:13
		with 'integrated circuit'	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	6		USPAT;	2002/08/21
		@ad<=20020109) and Copper adj bonding adj	US-PGPUB;	11:14
		pad ,	EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	2002/12/22
_	1143	@ad<=20020109 and cu adj 'bonding pad' with 'IMD' or 'intermetal dielectric'	USPAT; US-PGPUB;	2003/12/22
		with IMD of Intermetal diefectic	EPO; JPO;	12.10
	ļ		DERWENT;	
			IBM TDB	,
_	0	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2002/08/21
		with 'IMD'	US-PGPUB;	11:27
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	0	044.	USPAT;	2003/12/22
		with 'intermetal dielectric'	US-PGPUB;	12:00
		,	EPO; JPO;	
			DERWENT;	
		0.4<-20020100 2.4 24 15-24	IBM_TDB	2003/01/23
-	6	@ad<=20020109 and cu adj 'bonding pad' with 'Al'	USPAT; US-PGPUB;	2003/01/23
		with Mi	EPO; JPO;	""
	İ		DERWENT;	
		·	IBM TDB	
_	3	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2002/08/21
		and 'IMD'	US-PGPUB;	11:43
			EPO; JPO;	
			DERWENT;	
	Į		IBM_TDB	
_	1	"3942245".PN.	USPAT	2002/08/21
	_		HCDAT	11:40 2002/08/21
_	1	"5075965".PN.	USPAT	11:40
	1	"5288006".PN.	USPAT	2002/08/21
-	1	3200000 .PM.	ODEAL	11:40
_	1	"5376235".PN.	USPAT	2002/08/21
	1	3370233 .EN.		11:41
_	1 1	"5384284".PN.	USPAT	2002/08/21
	*	0001201 1111		11:41
_	1	"5436412".PN.	USPAT	2002/08/21
				11:42
	I	<u> </u>		<u> </u>

1	0	<pre>@ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric'</pre>	USPAT; US-PGPUB;	2003/12/23 09:52
			EPO; JPO; DERWENT;	
-	4	@ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric'	IBM_TDB USPAT; US-PGPUB;	2002/08/21
		pad and intermetal dielectric	EPO; JPO; DERWENT;	11:46
	809	(228/180.21).CCLS.	IBM_TDB USPAT;	2002/09/21
		(220/100.21/.ccls.	US-PGPUB; EPO; JPO;	2002/08/21 11:48
			DERWENT; IBM TDB	·
-	93	((228/180.21).CCLS.) and bonding adj pad	USPAT; US-PGPUB;	2002/08/21
			EPO; JPO; DERWENT;	11.30
_	9	((228/180.21).CCLS.) and bonding adj pad	IBM_TDB USPAT;	2002/08/21
		with copper	US-PGPUB; EPO; JPO;	13:32
			DERWENT; IBM TDB	
-	8	((228/180.21).CCLS.) and bond adj pad with copper	USPAT; US-PGPUB;	2002/08/21 13:30
	•	with copper	EPO; JPO; DERWENT;	13.30
_	0	((228/180.21).CCLS.) and bond adj pad	IBM_TDB USPAT;	2003/01/23
		with copper with 'Al' adj buffer	US-PGPUB; EPO; JPO;	08:45
			DERWENT; IBM TDB	
_	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al'	USPAT; US-PGPUB;	2002/08/21 13:31
			EPO; JPO; DERWENT;	
- .	639	ead<=20010119 and bonding adj pad with	IBM_TDB USPAT;	2002/08/21
	•	copper	US-PGPUB; EPO; JPO;	13:36
		·	DERWENT; IBM_TDB	
_	359	<pre>@ad<=20010119 and bonding adj pad with copper and aluminum</pre>	USPAT; US-PGPUB;	2002/08/21 13:47
			EPO; JPO; DERWENT;	
_	30	@ad<=20010119 and copper adj bonding adj	IBM_TDB USPAT;	2002/08/21
		pad and aluminum	US-PGPUB; EPO; JPO;	13:59
	0.25		DERWENT; IBM_TDB	2002/00/01
	839	@ad<=20010119 and bonding adj pad and aluminum and buffer	USPAT; US-PGPUB;	2002/08/21 14:00
			EPO; JPO; DERWENT; IBM TDB	
-	4120	'bonding pad' and apparatus	USPAT; US-PGPUB;	2002/08/21 15:03
			EPO; JPO; DERWENT;	
_	3573	((257/459) or (257/676) or (257/786) or	IBM_TDB USPAT;	2002/08/21
		(275/670) or (257/672)).CCLs.	US-PGPUB; EPO; JPO;	15:07
			DERWENT; IBM TDB	

_	1779	(438/612).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/01/23
			EPO; JPO; DERWENT;	00.47
_	1	bond adj pad with copper with 'Al' and	IBM_TDB USPAT;	2003/01/23
		'buffer'	US-PGPUB; EPO; JPO;	08:46
			DERWENT; IBM_TDB	
_	11	'bond' and 'pad' with copper with 'Al' and 'buffer'	USPAT; US-PGPUB;	2003/01/23 08:54
		·	EPO; JPO; DERWENT;	ļ.
_	284	(438/48).ccls. and @ad<=20020109	IBM_TDB USPAT;	2003/01/23
			US-PGPUB; EPO; JPO;	08:47
			DERWENT; IBM_TDB	
-	1722	(438/614).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/08/05 10:35
			EPO; JPO; DERWENT;	
-	573	(257/459).ccls. and @ad<=20020109	IBM_TDB USPAT; US-PGPUB;	2003/08/05
			EPO; JPO; DERWENT;	10:35
_	1222	(257/784).ccls. and @ad<=20020109	IBM_TDB USPAT;	2003/08/05
	1222	(23777047.CCIS. and gadv-20020103	US-PGPUB; EPO; JPO;	10:37
			DERWENT; IBM TDB	
-	1209	(257/786).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/08/05
		-	EPO; JPO; DERWENT;	
_	735	(257/781-782).ccls. and @ad<=20020109	IBM_TDB USPAT;	2003/08/05
			US-PGPUB; EPO; JPO;	10:40
			DERWENT; IBM TDB	·
	1392	(257/774).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/01/23 11:44
		,	EPO; JPO; DERWENT;	
_	1	'bond pad' with 'copper' with 'Al' and	IBM_TDB USPAT;	2003/01/23
		'buffer'	US-PGPUB; EPO; JPO;	08:55
			DERWENT; IBM_TDB	2002/01/22
_	1	'bonding pad' with 'copper' with 'Al' and 'buffer'	USPAT; US-PGPUB;	2003/01/23 08:56
			EPO; JPO; DERWENT;	
-	122	'bonding pad' with 'Cu' with 'Al'	IBM_TDB USPAT; US-PGPUB;	2003/01/23
			EPO; JPO; DERWENT;	
_	117	<pre>@ad<=20020109 and 'bonding pad' with 'Cu'</pre>	IBM_TDB USPAT;	2003/01/23
	** '	with 'Al'	US-PGPUB; EPO; JPO;	09:01
			DERWENT; IBM TDB	
L	I	<u> </u>		•

-	6	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2003/01/23	
		with 'Al'	US-PGPUB;	09:03	,
			EPO; JPO;		
			DERWENT;		ŀ
	225	0 1. 00000100 111 11 11 11 17	IBM_TDB		
- .	117	@ad<=20020109 and 'bonding pad' with 'Cu'	USPAT;	2003/08/05	!
		with 'Al'	US-PGPUB;	11:18	ĺ
			EPO; JPO;		ŀ
			DERWENT;		
}	,	WAO 11 00 1 W DAY	IBM_TDB	0000/01/00	
-	1	"4811081".PN.	USPAT	2003/01/23	
	,	WE 0.01 E 4.0 H . Day	110000	09:57	
-	1	"5001542".PN.	USPAT	2003/01/23	
1	1	"6108212".PN.	TICD NM	09:57	
-	1	6100212 .PN.	USPAT	2003/01/23	
	1	"6064120".PN.	IICDAM	2003/01/23	
_	1	0004120 .PN.	USPAT	09:58	
	246	 @ad<=20020109 and 'bonding pad' with	USPAT;	2003/01/23	
_	240	'integrated circuit' and 'Cu' and 'Al'	US-PGPUB;	10:02	
		Integrated critcuit and cd and Ar	EPO; JPO;	10.02	
			DERWENT;		
			IBM TDB		
	231	(257/784).ccls. and @ad<=20020109 and	USPAT;	2003/01/23	
	231	Copper' and 'aluminum'	US-PGPUB;	10:38	
		Copper and arminimin	EPO; JPO;	10.30	.
			DERWENT;		
			IBM TDB		Ì
_	2356	(438/612).ccls. or (438/597).ccls. and	USPAT;	2003/08/05	ł
		@ad<=20020109	US-PGPUB;	10:34	-
		3	EPO; JPO;		}
		·	DERWENT;		
			IBM TDB		
	798	(228/180.21).ccls. and @ad<=20020109	USPAT;	2003/08/05	
		•	US-PGPUB;	10:35	.
			EPO; JPO;		
			DERWENT;	•	
			IBM TDB		ŀ
-	2531	(438/613-617).ccls. and @ad<=20020109	USPAT;	2003/08/05	}
			US-PGPUB;	10:38	ł
			EPO; JPO;		ŀ
			DERWENT;		ŀ
			IBM_TDB		
-	586	(257/459).ccls. and @ad<=20020109	USPAT;	2003/08/05	
	1		US-PGPUB;	10:39	
			EPO; JPO; DERWENT;	1	
				}	
_	1320	(257/784).ccls. and @ad<=20020109	IBM_TDB USPAT;	2003/08/05	
		\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	US-PGPUB;	10:40	
		· ·	EPO; JPO;	*****	
			DERWENT;	1	
			IBM TDB	1	.
-	1288	(257/786).ccls. and @ad<=20020109	USPAT;	2003/08/05	
			US-PGPUB;	10:42	
			EPO; JPO;	1	
			DERWENT;	,	
			IBM_TDB	l	
	782	(257/781-782).ccls. and @ad<=20020109	USPAT;	2003/08/05	
			US-PGPUB;	10:44	
			EPO; JPO;	1	
			DERWENT;		
	1500	(057/676)	IBM_TDB	0000 100 105	
-	1782	(257/676).ccls. and @ad<=20020109	USPAT;	2003/08/05	İ
			US-PGPUB;	10:46	
			EPO; JPO;		1
			DERWENT;	1	- 1
L	<u> </u>		IBM TDB	L	

-	27	<pre>@ad<=20020109 and 'bonding pad' near3 'Cu' with 'Al'</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/05
-		@ad<=20020109 and 'bonding pad' near3 'Copper' with 'Aluminum'	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/05
_	34	@ad<=20020109 and CVC.as. and interconnect	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/05
-	1	("6333559").PN.	IBM_TDB USPAT	2003/08/05
-	4	(("5785236") or ("6197613") or ("6162652") or ("6555759")).PN.	USPAT	11:38 2003/08/05 11:40
-	. 0	"20020164840"	USPAT	2003/08/05
-	0	"2002/0164840"	USPAT	2003/08/05
-	2	"20020164840"	USPAT; US-PGPUB;	2003/08/05 11:42
			EPO; DERWENT; IBM TDB	
-	2	"20010035452"	USPAT; US-PGPUB; EPO;	2003/08/05
-	2	"20020047218"	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/08/05
	4	"2003012776"	EPO; DERWENT; IBM_TDB	2002/12/22
	4		USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/22
-	2 .	"20030127716"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/22 11:23
-	0	<pre>@ad<=20020109 and 'wiring bonding pad' and 'intermetal dielectric' and 'metal layer'</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/22 12:04
	0	<pre>@ad<=20020109 and 'wiring bonding pad' and 'intermetal dielectric'</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/22 12:04
-	209	@ad<=20020109 and 'wiring bonding pad'	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/22 12:10
-	22	@ad<=20020109 and 'wiring bond pad'	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/22 12:04

-	44	@ad<=20020109 and 'copper' and 'bonding	USPAT;	2003/12/22
		pad' and 'IMD'	US-PGPUB; EPO; JPO;	12:48
			DERWENT;	
			IBM_TDB	0000/10/100
_	40	<pre>@ad<=20020109 and 'copper' and 'bond pads' and 'IMD'</pre>	USPAT; US-PGPUB;	2003/12/22
		pado did III	EPO; JPO;	12.30
			DERWENT;	
_	69	@ad<=20020109 and 'bond pads' and 'IMD'	IBM_TDB USPAT;	2003/12/22
		The state of the s	US-PGPUB;	12:54
			EPO; JPO;	
			DERWENT; IBM TDB	
-	107	@ad<=20020109 and 'bond pads' same	USPAT;	2003/12/22
		'mechanical stress'	US-PGPUB; EPO; JPO;	12:59
			DERWENT;	
			IBM_TDB	0000 (00 (00
_	108	<pre>@ad<=20020109 and 'bonding pad' same 'mechanical stress'</pre>	USPAT; US-PGPUB;	2003/12/22 12:59
		weenanteat perenn	EPO; JPO;	12.05
			DERWENT;	
_	1	@ad<=20020109 and 'bond pads' same	IBM_TDB USPAT;	2003/12/23
	-	'buffer layer' same 'bonding layer'	US-PGPUB;	09:54
		\cdot	EPO; JPO;	
			DERWENT; IBM TDB	
_	i	@ad<=20020109 and 'bonding pad' same	USPAT;	2003/12/23
		'buffer' same 'bonding layer'	US-PGPUB; EPO; JPO;	09:57
			DERWENT;	-
	107		IBM_TDB	0000/10/00
-	13	<pre>@ad<=20020109 and 'UBM' and 'bond pads' and 'buffer' and 'bonding'</pre>	USPAT; US-PGPUB;	2003/12/23
0		and parter and ponding	EPO; JPO;	10.00
		·	DERWENT;	
_	497	@ad<=20020109 and 'bond pads' and 'EDS'	IBM_TDB USPAT;	2003/12/23
			US-PGPUB;	10:12
	*		EPO; JPO; DERWENT;	9.2
			IBM TDB	
-	2	@ad<=20020109 and 'bond pads' with 'EDS'	USPAT;	2003/12/23
			US-PGPUB; EPO; JPO;	10:03
			DERWENT;	
	315	chou.in. and taiwan	IBM_TDB USPAT;	2003/12/23
	315	CHOU.III. AND CAIWAN	USPAT; US-PGPUB;	10:06
			EPO; JPO;	
			DERWENT; IBM TDB	
_	0	chou-kuo.in.	USPAT;	2003/12/23
			US-PGPUB;	10:04
		•	EPO; JPO; DERWENT;	
			IBM_TDB	
-	25	kuo-yu.in.	USPAT;	2003/12/23
			US-PGPUB; EPO; JPO;	10:06
			DERWENT;	
	1	Made=20020109 and leingle layer! non-	IBM_TDB	2003/12/23
	1	<pre>@ad<=20020109 and 'single layer' near 'wiring bond pad'</pre>	USPAT; US-PGPUB;	2003/12/23
		• · · · · · · · · · · · · · · · · · · ·	EPO; JPO;	
			DERWENT; IBM TDB	
L	I		TOM IND	

_	22	@ad<=20020109 and 'wiring bond pad'	USPAT;	2003/12/23
		·	US-PGPUB;	10:13
			EPO; JPO;	
			DERWENT;	[
			IBM TDB	